DECEMBER 1983-REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPe
- Dependable Texas Instruments Quality and Reliability

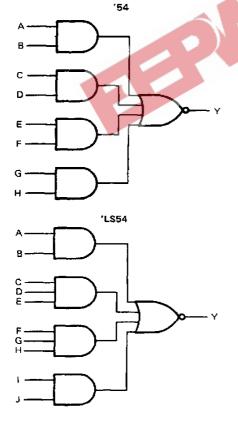
description

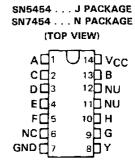
These devices contain 4-wide AND-OR-INVERT gates. They perform the following Boolean functions:

'54 Y =
$$\overrightarrow{AB}$$
 + \overrightarrow{CD} + \overrightarrow{EF} + \overrightarrow{GH}
LS54 Y = \overrightarrow{AB} + \overrightarrow{CDE} + \overrightarrow{FGH} + \overrightarrow{IJ}

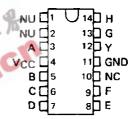
The SN5454 and SN54LS54 are characterized for operation over the full military temperature range of $-55\,^{\circ}\text{C}$ to 125 $\,^{\circ}\text{C}$. The SN7454 and SN74LS54 are characterized for operation from 0 $\,^{\circ}\text{C}$ to 70 $\,^{\circ}\text{C}$.

logic diagrams (positive logic)

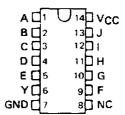




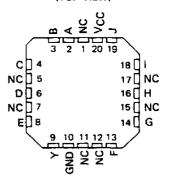
SN5454 . . . W PACKAGE (TOP VIEW)



SN54LS54 . . . J OR W PACKAGE SN74LS54 . . . D OR N PACKAGE (TOP VIEW)



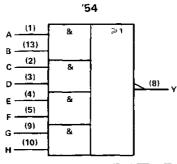
SN54LS54 . . . FK PACKAGE (TOP VIEW)



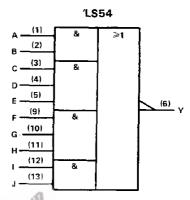
NC-No internal connection
NU-Make no external connection

SN5454, SN54LS54, SN7454, SN74LS54 4-WIDE AND-OR-INVERT GATES

logic symbols†

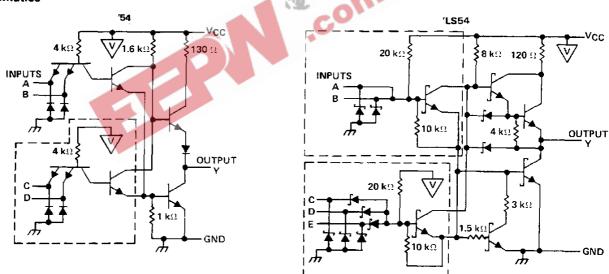


positive logic: $Y = \overline{A8 + CD + EF + GH}$



positive logic: $Y = \overline{AB + CDE + FGH + IJ}$

schematics



Resistor values shown are nominal.

The portion of the circuits within the dashed lines is repeated for each additional 2- or 3-input AND section, as shown in the logic diagram and logic symbols.

[†]These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, and N package. For the SN54LS54 only, they apply also for the W package.

SN5454, SN7454 4-WIDE AND-OR-INVERT GATES

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note	1)	7 V
Input voltage		5.5 V
	SN5454	
, ,	SN7454	0°C to 70°C
Storage temperature range		-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

			SN5454				UNIT		
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage		2			2			٧
VIL	Low-level input voltage			4	9.0			8.0	٧
ТОН	High-level output current		ۋىد ي	, /10	- 0.4		-	- 0.4	mΑ
IOL	Low-level output current		61	_0	16			16	mA
TA	Operating free-air temperature	12.19	- 55	C	125	0		70	°C

electrical characterics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	Tret countries of	SN5454	SN7454	UNIT
	TEST CONDITIONS [†]	MIN TYP\$ MAX	MIN TYP MAX	UNIT
Vik	$V_{CC} = MIN$, $I_{j} = -12 \text{ mA}$	- 1.5	- 1.5	٧
VOH	$V_{CC} = MIN$, $V_{1L} = 0.8 \text{ V}$, $I_{OH} = -0.4 \text{ mA}$	2.4 3.4	2.4 3.4	٧
VOL	V _{CC} = MIN. V _{1H} = 2 V, I _{OL} = 16 mA	0.2 0.4	0.2 0.4	٧
l _l	V _{CC} = MAX, V _I = 5.5 V	1	1	mA
Чн	V _{CC} = MAX, V _I = 2.4 V	40	40	μΑ
l L	V _{CC} = MAX, V ₁ = 0.4 V	- 1.6	- 1.6	mA
losÿ	V _{CC} = MAX	- 20 - 55	- 18 - 55	mA
ГССН	V _{CC} = MAX, V _I = 0 V	4 8	4 8	mΑ
CCL	V _{CC} = MAX, See Note 2	5.1 9.5	5.1 9.5	mΑ

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN TYP	MAX	UNIT
[†] PLH	Апу	· ·	R ₁ = 400 Ω. C ₁ = 15 pF	13	22	ns
^t PHL	Ally	· · · · · · · · · · · · · · · · · · ·	7 C - 400 12; C - 15 F	8	15	ns -

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. § Not more than one output should be shorted at a time.

NOTE 2: All inputs of one AND gate at 4.5 V, all others at GND.

SN54LS54, SN74LS54 4-WIDE AND-OR-INVERT GATES

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note	1)	7 V
Input voltage	***************************************	7 V
Operating free-air temperature:	SN54LS54	°C to 125°C
	SN74LS54 (°C to 70°C
Storage temperature range		°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

			SN54LS54		SN74LS54				
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage		2	A .		2			٧
VIL	Low-level input voltage		37	TO TO	0.7			8.0	V
Гон	High-level output current	_ 4	4		- 0.4		_	- 0.4	mΑ
OL	Low-level output current	. %.	1	-3/1	4			8	mΑ
τ _A	Operating free-air temperature	20 %	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS54			SN74LS54			T
	TEST CONSTITUTES.	MIN	TYP‡	MAX	MIN	TYP \$	MAX	UNIT
V _{IK}	V _{CC} = MIN, I ₁ = 18 mA			- 1.5			- 1.5	V
Voн	VCC = MIN, VIL = MAX, IOH = -0.4 mA	2.5	3.4		2.7	3.4		V
VOL	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 4 mA		0.25	0.4		0.25	0.4	1.
	$V_{CC} = MIN$, $V_{IH} = 2 V$, $I_{OL} = 8 mA$	T				0.35	0.5	· ·
Ξ	V _{CC} = MAX, V _I = 7 V	T		0.1			0.1	mΑ
ПH	V _{CC} = MAX, V ₁ = 2.7 V			20			20	μА
1 <u>1</u> L	V _{CC} = MAX, V ₁ = 0.4 V	T		- 0.4			- 0.4	mΑ
los§	V _{CC} = MAX	- 20		- 100	- 20		– 100	mΑ
Іссн	V _{CC} = MAX, V _I = 0 V		0.8	1.6		8.0	1.6	mΑ
'CCL	V _{CC} = MAX, See Note 2	Ţ	1	2		1	2	mΑ

 $^{^\}dagger$ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, VCC = 5 V, $T_A = 25^{\circ} \text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
tPLH tPHL	Any	Y	$R_L \approx 2 k\Omega$, $C_L = 15 pF$		12 12.5	20 20	กร กร

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{ C}$. §Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second. NOTE 2: All inputs of one AND gate at 4.5 V, all others at GND.





www.ti.com 26-Sep-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN5454J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54LS54J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54LS54J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN7454N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7454N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS54D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS54D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS54DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS54DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS54J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS54J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS54N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS54N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SNJ5454J	ACTIVE	CDIP	J	14	186	TBD 🥒	Call TI	Level-NC-NC-NC
SNJ5454J	ACTIVE	CDIP	J	14	1/2	TBD	Call TI	Level-NC-NC-NC
SNJ5454W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ5454W	ACTIVE	CFP	W	14		TBD	Call TI	Level-NC-NC-NC
SNJ54LS54FK	OBSOLETE			20		TBD	Call TI	Call TI
SNJ54LS54FK	OBSOLETE		I	20		TBD	Call TI	Call TI
SNJ54LS54J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS54J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS54W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS54W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM

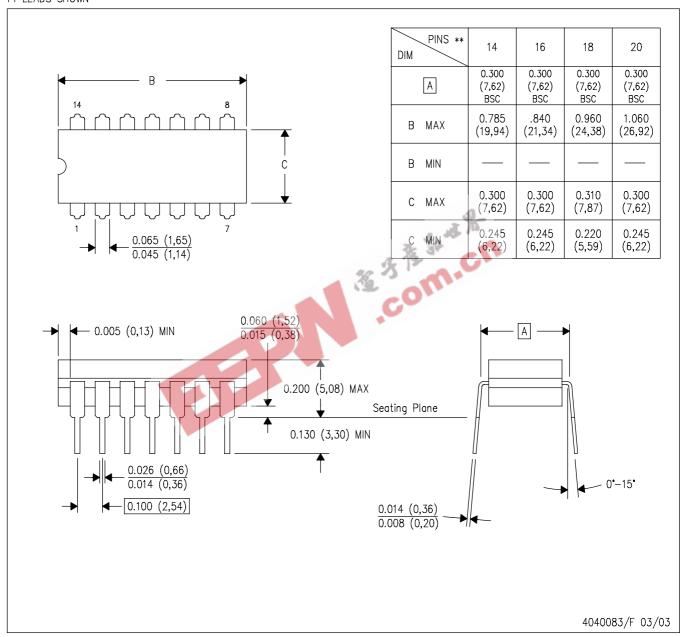
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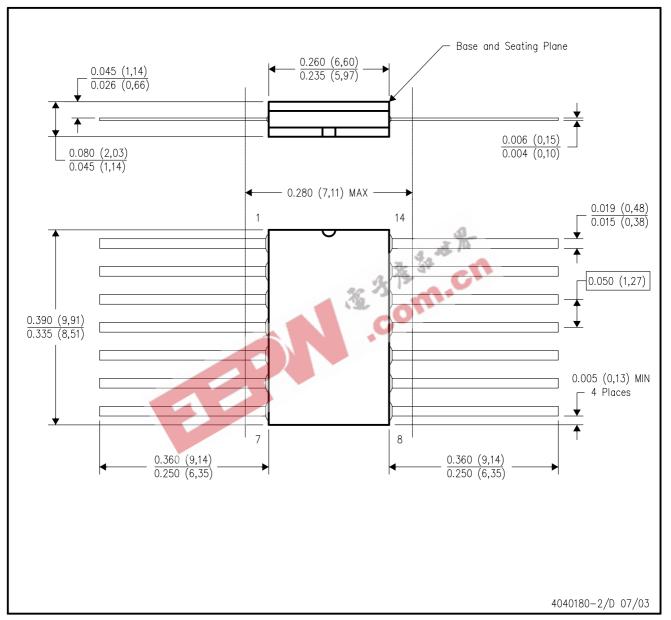
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- $E. \quad \text{Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.} \\$

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



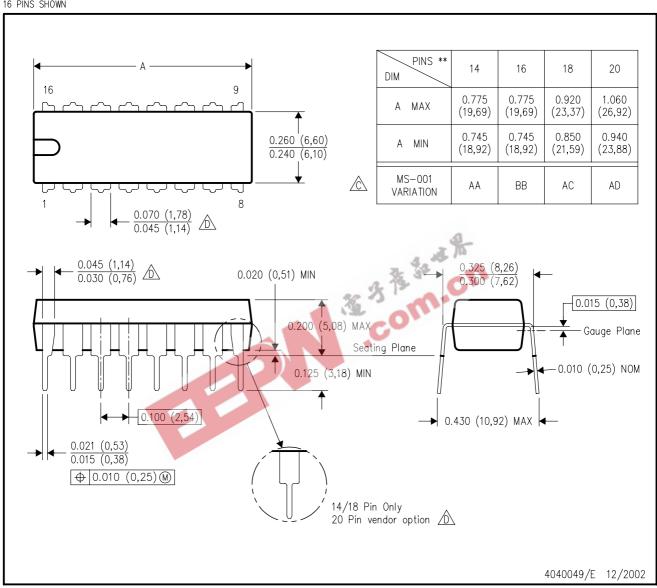
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

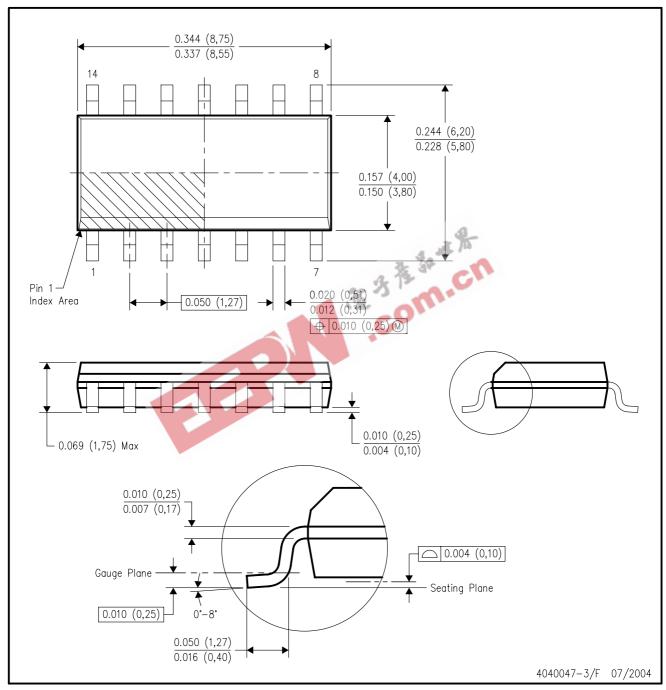
16 PINS SHOWN



- All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



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